ADC9708

ADC9708 6-Channel 8-Bit MuP Compatible A/D Converter

Literature Number: SNOS548A

National Semiconductor

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ADC9708
6-Channel 8-Bit μP Compatible A/D Converter

General Description

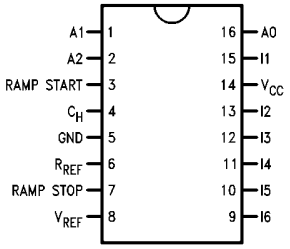
The ADC9708 is a single slope 8-bit, 6-channel ADC subsystem that provides all of the necessary analog functions for a microprocessor-based data control system. The device uses an external microprocessor system to provide the necessary addressing, timing and counting functions and includes a 1-of-8 decoder, 8-channel analog multiplexer, sample and hold, ramp integrator, precision ramp reference, and a comparator on a single monolithic chip.

Features

- MPU compatible
- Excellent linearity over full temperature range ±0.2% maximum
- Typical 300 μs conversion time per channel
- Wide dynamic range includes ground
- Auto-zero and full-scale correction capability
- Ratiometric conversion—no precision reference required
- Single-supply operation
- TTL compatible
- Does not require access to data bus or address bus

Connection Diagram

All Packages



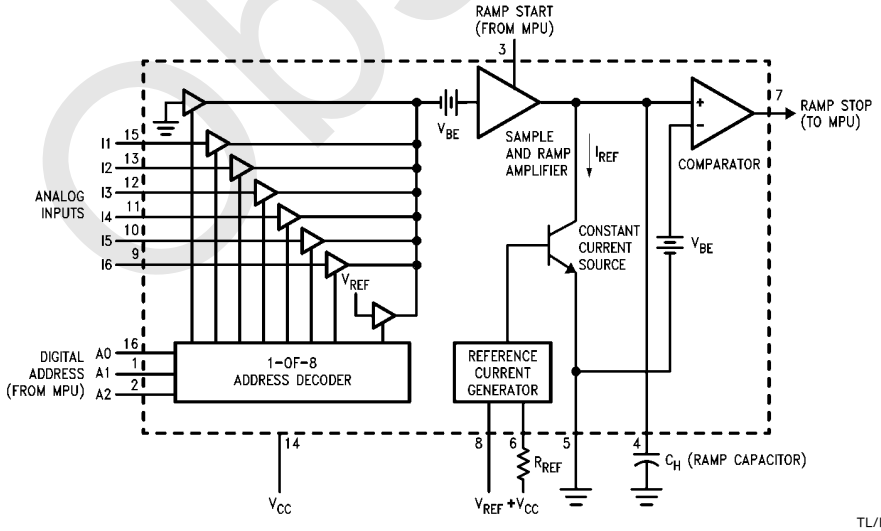
TL/H/10409–2

(Top View)

Ordering Information

Commercial ($0°C \le T_A \le 70°C$)	Package
ADC9708CCN	N16E
ADC9708CCJ	J16A
Military ($-55°C \le T_A \le 125°C$)	**Package**
ADC9708CMJ	J16A

Block Diagram



TL/H/10409–1

RRD-B30M115/Printed in U. S. A.

Absolute Maximum Ratings (Notes 1, 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC})	18V
Comparator Output (Ramp Stop)	−0.3V to +18V
Analog Input Range	−0.3V to +30V
Digital Input Range	−0.3V to +30V
Output Sink Current	10 mA
Storage Temperature Range	−65°C to +150°C
Continuous Total Dissipation (Note 8)	
Ceramic DIP Package	900 mW
Molded DIP Package	1000 mW
ESD Susceptibility (Note 9)	TBD
Pin Temperature	
Ceramic DIP (Soldering, 60 Sec.)	300°C
Molded DIP (Soldering, 10 Sec.)	260°C

Operating Ratings (Notes 1, 2)

Operating Temperature Range	
ADC9708CCN, ADC9708CCJ	0°C to +70°C
ADC9708CMJ	−55°C to +125°C
Supply Voltage (V_{CC})	4.75V to 15V
Reference Voltage (V_{REF}) (Note 3)	2.8V to 5.25V
Ramp Capacitor (C_H)	300 pF
Reference Current (I_R)	12 μA to 50 μA
Analog Input Range	0V to V_{REF}
Ramp Stop Output Current	1.6 mA

Electrical Characteristics

Over recommended operating conditions, V_{CC} = 5.0V, −55°C ≤ T_A ≤ +125°C for ADC9708CMJ and 0°C ≤ T_A ≤ +70°C for ADC9708CCJ or ADC9708CCN; unless otherwise specified.

Symbol	Parameter		Conditions	Typical (Note 10)	Limit (Note 11)	Units (Limit)
E_A	Conversion Accuracy		Over Entire Temperature Range (Note 4)	±0.2	±0.3	% (max)
E_R	Linearity		Applies to Any One Channel (Note 5)	±0.08	±0.2	% (max)
V_{OSM}	Multiplexer Input Offset Voltage		Channel ON, T_A = 25°C	2.0	4.0	mV (max)
			Channel ON	2.0	7.0	mV (max)
t_C	Conversion Time per Channel		Analog Input = 0V to V_{REF} C_H = 300 pF, I_{REF} = 50 μA	296	350	μs (max)
t_A	Acquisition Time		C_H = 1000 pF	20	40	μs (max)
I_A	Acquisition Current	ADC9708CCN, CCJ			150	μA (min)
		ADC9708CMJ			115	μA (min)
t_O	Ramp Start Delay Time			100		ns
t_M	Multiplexer Address Time			1.0		μs
V_{IH}	Digital Input HIGH Voltage		A0, A1, A2, Ramp Start		2.0	V (min)
V_{IL}	Digital Input LOW Voltage		A0, A1, A2, Ramp Start		0.8	V
I_B	Analog Input Current		Channel ON or OFF	−1.0	−3.0	μA (min)
I_{IL}	Input LOW Current		A0, A1, A2, Ramp Start = 0.4V	−5	−15	μA (min)
I_{IH}	Input HIGH Current		A0, A1, A2, Ramp Start = 5.5V		1.0	μA (max)
I_{OS}	Input Offset Current			1.0	3.0	μA (max)
I_{OH}	Comparator Logic "1" Output Leakage Current		V_{OH} = 15V		10	μA (max)
V_{OL}	Comparator Logic "0" Output Voltage		I_{OL} = 1.6 mA		0.4	V (max)
PSRR	Power Supply Rejection Ratio		(Note 6)		40	dB (min)
	Cross Talk between Any Two Channels		(Note 7)		60	dB (min)

Electrical Characteristics

Over recommended operating conditions, $V_{CC} = 5.0V$, $-55°C \leq T_A \leq +125°C$ for ADC9708CMJ and $0°C \leq T_A \leq +70°C$ for ADC9708CCJ or ADC9708CCN; unless otherwise specified. (Continued)

Symbol	Parameter	Conditions	Typical (Note 10)	Limit (Note 11)	Units (Limit)
I_{CC}	Power Supply Current	$V_{CC} = 5V$ to 15V, I0 = 0	7.5	15	mA (max)
C_{IN}	Input Capacitance		3.0		pF
C_{OUT}	Comparator Output Capacitance		5.0		pF

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional. These ratings do not guarantee specific performance limits, however. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Note 2: All voltages are measured with respect to GND, unless otherwise specified.

Note 3: V_{REF} should not exceed $V_{CC} - 2V$.

Note 4: Conversion accuracy is defined as the deviations from a straight line drawn between the points defined by channel address 000 (0 scale) and channel address 111 (full scale) for all channels.

Note 5: Linearity is defined as the deviation from a straight line drawn between the 0 and full scale points for each channel.

Note 6: Power supply rejection ratio is defined as the conversion error contributed by power supply voltage variations while resolving mid scale on any channel.

Note 7: Cross Talk between channels $= 20 \log \frac{\Delta V_{CH}}{\Delta V_I}$.

Note 8: Caution should be taken not to exceed absolute maximum power rating when the device is operating in a severe fault condition (ex. when any inputs or outputs exceed the power supply). The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (package junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $P_{Dmax} = (T_{Jmax} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower. For this device, $T_{Jmax} = 150°C$, and the typical thermal resistance (θ_{JA}) for board mounting follow:

ADC9708CCN	62°C/W
ADC9708CCJ, ADC9708CMJ	58°C/W

Note 9: Human body model, 100 pF discharged through a 1.5 kΩ resistor.

Timing Diagram

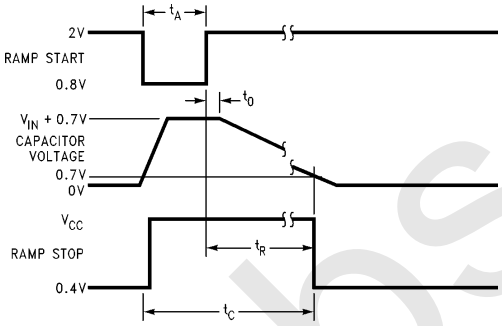
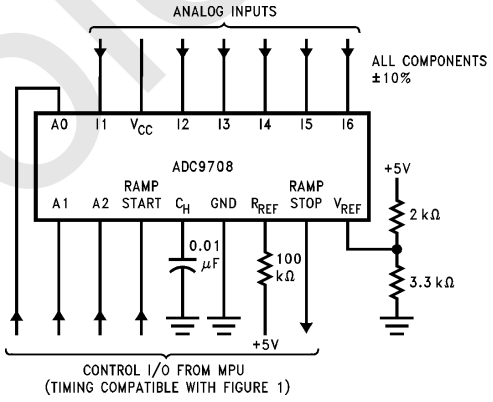


FIGURE 1. Equivalent Timing Waveform for Test Circuits and Applications

Note 10: Typicals are at +25°C and represent most likely parametric norm.

Note 11: Tested limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

Test Circuits



Input Timing:

$t_A > 400\ \mu s$

$V_{REF} = \left(\frac{3.3\ k\Omega}{2\ k\Omega + 3.3\ k\Omega}\right) 5V = 3.1$

$I_R = \frac{5 - 3.1}{100\ k\Omega} = 19\ \mu A$

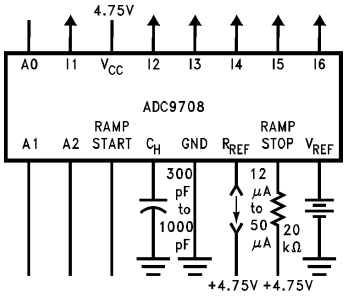
$t_R|_{max}$ = full scale ramp time

$= \frac{0.01 \times 10^{-6}}{19 \times 10^{-6}} \times 3.1 = 1.6\ ms$

Note: For evaluation purposes,the ramp start timing generation can be implemented with an LM555 timer (astable operation) or MPU evaluation kit, and a time interval meter for ramp time measurement. The TIM meter will measure the time between to 0 to 1 transition of the ramp start and the 1 to 0 transition of the ramp stop. The ramp stop is open collector, and must have an external pull-up resistor to V_{CC}.

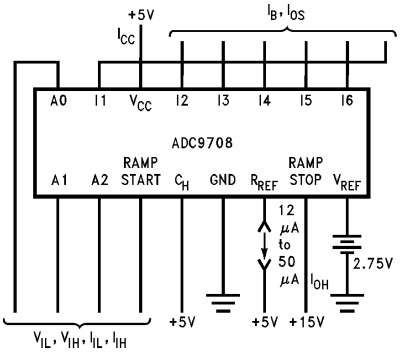
FIGURE 2. Slow Speed Evaluation Circuit for Ratiometric Operation

Test Circuits (Continued)



TL/H/10409–9

FIGURE 3. Linearity/Acquisition Time/ Conversion Time Test Circuit



TL/H/10409–10

FIGURE 4. Static Measurements

Functional Description

This Analog to Digital Converter is a single-slope 8-bit, 6-channel A/D converter that provides all of the necessary analog functions for a microprocessor-based data/control system. The device uses the processor system to provide the necessary addressing, timing and counting functions and includes a 1-of-8 decoder, 8-channel analog multiplexer, sample and hold, precision current reference, ramp integrator and comparator on a single monolithic chip.

Applications that require auto-zero or auto-calibration, (See *Figures 5–8*) can use selection of address 000 and 111, for input address lines A0–A2, in conjunction with the arithmetic capability of a microprocessor to provide ground and scaling factors. Address 0, 0, 0 internally connects the input of the ramp generator to ground and may be used for zero offset correction in subsequent conversions. Address 1, 1, 1, internally connects the input of the ramp generator to the voltage reference, V_{REF}, and may be used for scale factor correction in subsequent conversions. For the following, refer to the Functional Block Diagram.

Six separate external analog voltage inputs may come into terminals I1–I6 and the specific analog input to be converted is selected via address terminals A0–A2. The analog input voltage level is transferred to the external ramp capacitor connected to pin 4 when the input to the ramp start terminal (pin 3) is at a logic 0 (See *Figure 1*). The time to charge the capacitor is the acquisition time which is a function of the output impedance of an amplifier internal to the A/D converter and the value of the capacitor. After charging the external capacitor the ramp start terminal is switched to a logic 1 which introduces a high impedance between the analog input voltage and the external capacitor.

The capacitor begins to discharge at a controlled rate. The controlled rate of discharge (ramp) is established by the external reference voltage, the external reference resistor, the value of the external capacitor and the internal leakage of the A/D converter. Connected to the capacitor terminal is a comparator internal to the A/D converter with its output going to the ramp stop terminal (pin 7). The comparator output is a logic one when the capacitor is charged and switches to a logic 0 when the capacitor is in a discharged state. The ramp time is from the time when ramp start goes HIGH (logic "1") to when ramp stop goes LOW (logic "0"). The microprocessor must be programmed to determine this conversion time. The ideal (no undesirable internal source impedances, leakage paths, errors on levels where comparator switches or delay time) conversion time is calculated as follows:

$$\text{Ramp Time} = V1 \frac{C_H}{I_R}$$

Where $V1$ = Analog Input Voltage Being Measured
C_H = External Ramp Capacitor

$$I_R = \frac{V_{CC} - V_{REF}}{R_{REF}}$$

Where V_{CC} = Power Supply Voltage
V_{REF} = Reference Voltage
R_{REF} = Reference Resistor

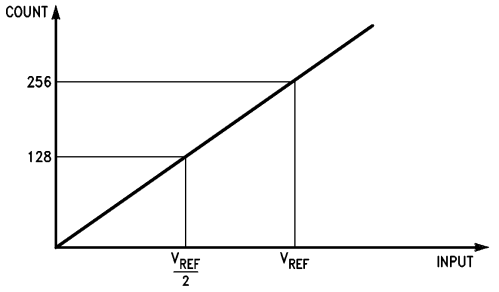
In actual use the errors due to a nonideal A/D converter can be minimized by using a microprocessor to make the calculations. (See *Figures 5* through *8*.)

Channel Selection

Input Address Line			Selected Analog Input
A2	A1	A0	
0	0	0	Ground
0	0	1	I1
0	1	0	I2
0	1	1	I3
1	0	0	I4
1	0	1	I5
1	1	0	I6
1	1	1	V_{REF}

Functional Description (Continued)

Auto-Zero and Full-Scale Features

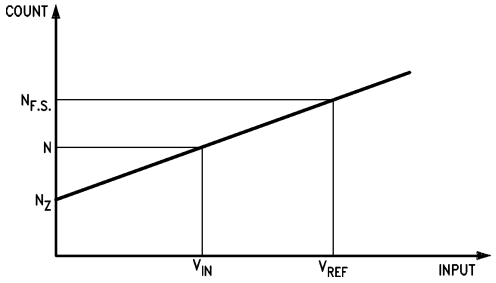


No Zero Offset
No Full-Scale Error

TL/H/10409–3

$$\text{Count (n)} = \frac{V_{IN}}{V_{REF}} \times 256$$

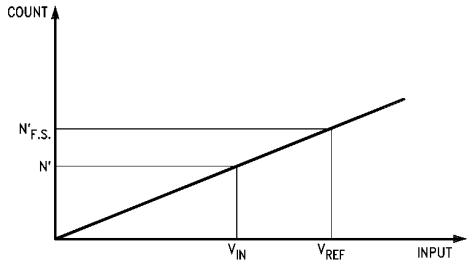
FIGURE 5. Ideal Transfer Function



$N_{F.S.} \neq 256$
$N_Z \neq 0$
(N) has both full-scale and zero errors

TL/H/10409–4

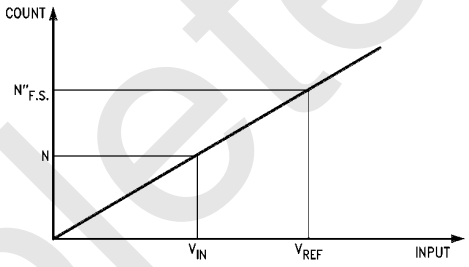
FIGURE 6. Transfer Function with Zero and Full-Scale Error



$N' = N - N_Z$
N′ has Full-Scale Error

TL/H/10409–5

FIGURE 7. Transfer Functions with Zero-Correction Added



$$N'' = (N - N_Z) \times \frac{256}{(N_{F.S.} - N_Z)}$$

TL/H/10409–6

FIGURE 8. Transfer Function with both Zero and Full-Scale Correction Added

Typical Applications

Application Suggestions and Formulas

1. The capacitor node impedance is approximately 30 $\mu\Omega$ and should have no parallel resistance for proper operation.
2. t_R when $V_{IN} = 0V$ will be finite (i.e., the comparator will always toggle for $V_{IN} \geq 0V$).
3. The ramp stop output is open collector, and an external pull-up resistor is required.
4. All digital inputs and outputs are TTL compatible.
5. For proper operation, timing commences on the 0 to 1 transition of ramp start and terminates on the 1 to 0 transition of ramp stop.
6. $t_A \geq \frac{C_H}{I_A - I_R} \times V_{REF}$ (See *Figure 1*)
7. t_R (ramp time) $= \frac{C_H}{I_R} \times V_{IN}$, $t_R|_{max} = \frac{C_H}{I_R} \times V_{REF}$
   (See *Figure 1*)
8. $I_R = \frac{V_{CC} - V_{REF}}{R_{REF}}$
9. $2V \leq V_{REF} \leq (V_{CC} - 2V)$
10. Address lines A0, A1, A2 must be stable throughout the sampling interval, t_A.
11. Pin 6 (R_{REF}) should be bypassed to ground via a 0.02 μF capacitor.

Microprocessor Considerations

Several alternatives exist from a hardware/software standpoint in microprocessor based systems using the ADC9708.

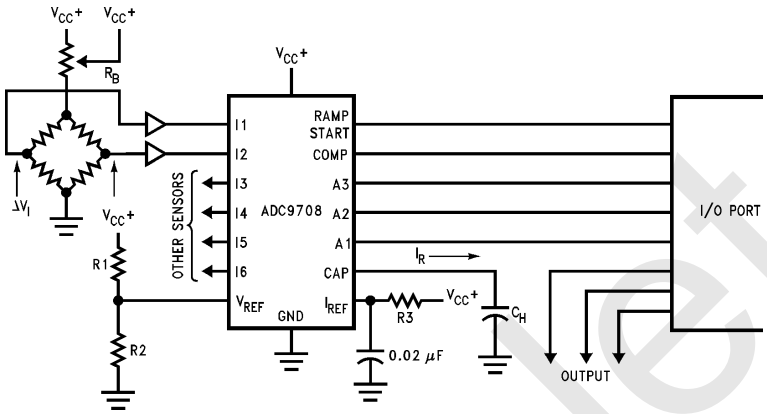
1. The ramp time measurement may be implemented in software using a register increment, followed by a branch back depending on the status of the ramp stop.
2. Alternately, the ramp stop may be tied into the interrupt structure in systems containing a programmable binary timer. This scheme has the following advantages:
   a. The CPU is not committed during the ramp time interval.
   b. It requires only 5 bits of an I/O port for control signals.

Typical Applications (Continued)

3. The auto-zero/auto-full-scale (See *Figures 5–8*) should use double precision, rounded (as opposed to truncated) arithmatic. Several points are worth noting:
   a. The subtractions are single op code instructions.
   b. The full scale correction uses a multiply by 256 and can be accomplished by a shift left 8 bits (usually one instruction) or placing ($N - N_Z$) in the MSB register and setting the LSB register to zero, for the double precision divide.
   c. The divisor ($N_{F.S.} - N_Z$) of the MSB register will always be zero.

These schemes have the following advantages:

a. No access to the data bus or address bus is required, by the A/D system.
b. 5 I/O bits completely support the A/D system.
c. Since auto full scale/auto zero are implemented in software and long term drift (aging) effects are eliminated.
d. Software overhead is minimal (typically 30 bytes).
e. Where ratiometric operation is permissible, the 4 external components may be ±5% tolerance, including the power supply.



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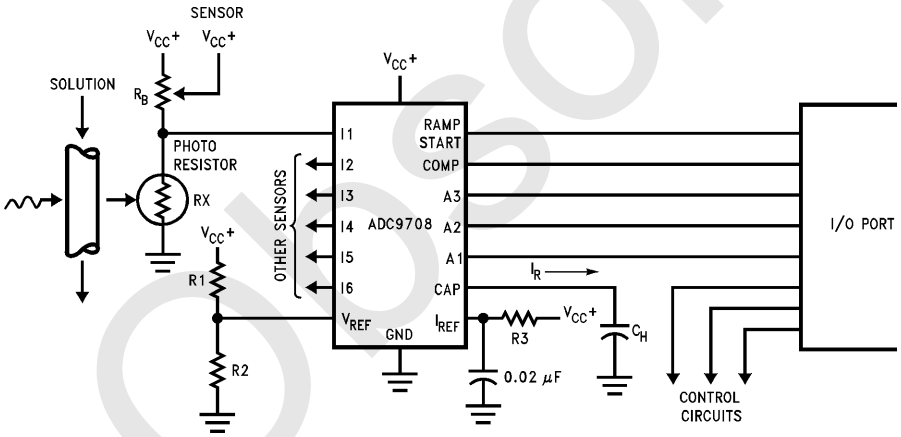
Note: ΔV_I = (Applied Force) and can be Linearized (if necessary) in Software.

FIGURE 9. Ratiometric Strain Gage Sensore/Controller



TL/H/10409–12

Applications
Beverage Brewers/Dispensers
Chemical Solution Control
Automatic Liquid Mixing Control

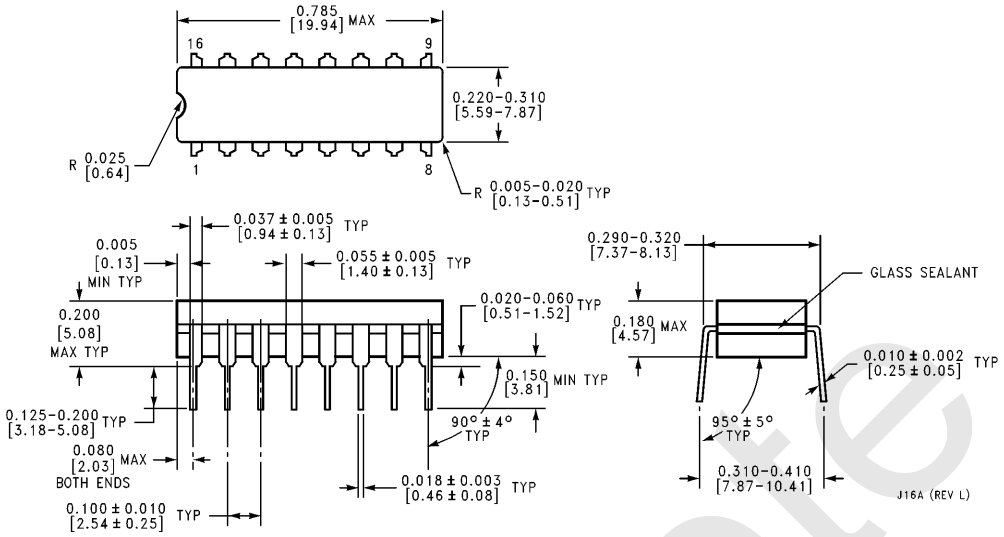
$$\text{Ramp Current} = I_R = V_{CC^+} \left(\frac{R_1}{R_1 + R_2}\right)\left(\frac{1}{R_3}\right)$$

$$V_I = \left(\frac{R_X}{R_X + R_B}\right) V_{CC^+}$$

$$\text{Ramp Time} = V_I \left(\frac{C_H}{I_R}\right) = \left(\frac{R_X}{R_X + R_B}\right)\left(1 + \frac{R_2}{R_1}\right)\left(C_H R_3\right)$$

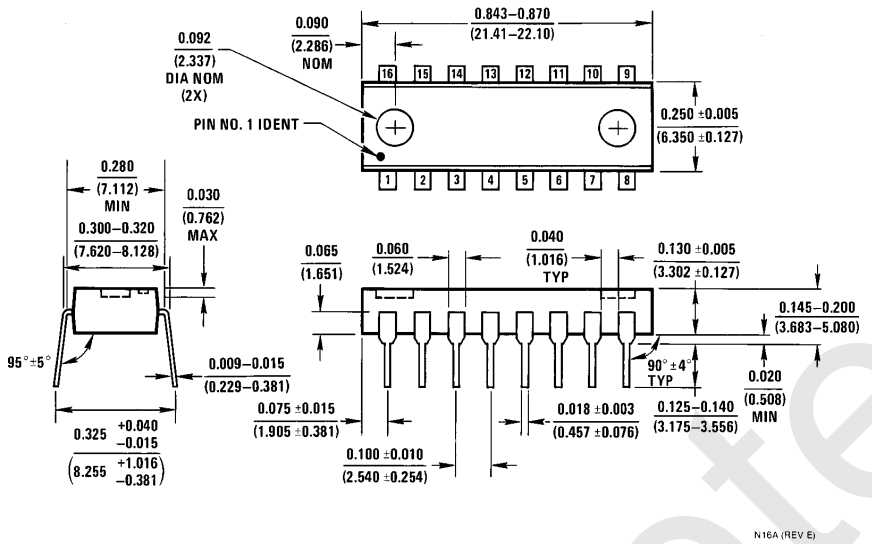
FIGURE 10

Physical Dimensions inches (millimeters)



Dual-In-Line Package (J)
Order Number ADC9708CCJ or ADC9708CMJ
NS Package Number J16A

Physical Dimensions inches (millimeters) (Continued)



16 Lead Dual-In-Line Package (N)
Order Number ADC9708CCN
NS Package Number N16E

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